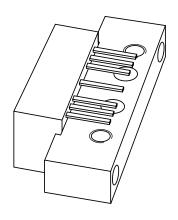
DISCRETE SEMICONDUCTORS

DATA SHEET



BGD802 860 MHz, 18.5 dB gain power doubler amplifier

Product specification Supersedes data of 2001 Oct 30 2002 Jan 23



860 MHz, 18.5 dB gain power doubler amplifier

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FEATURES

- · Excellent linearity
- · Extremely low noise
- · Excellent return loss properties
- Silicon nitride passivation
- Rugged construction
- · Gold metallization ensures excellent reliability.

APPLICATIONS

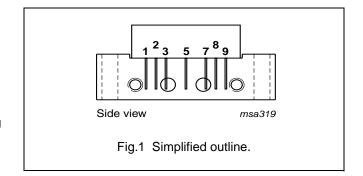
 CATV systems operating in the 40 to 860 MHz frequency range.

DESCRIPTION

Hybrid amplifier module in a SOT115J package operating at a supply voltage of 24 V (DC).

PINNING - SOT115J

PIN	DESCRIPTION
1	input
2, 3	common
5	+V _B
7, 8	common
9	output



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Gp	power gain	f = 50 MHz	18	19	dB
		f = 860 MHz	18.5	_	dB
I _{tot}	total current consumption (DC)	V _B = 24 V	_	410	mA

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER		MAX.	UNIT
V_B	supply voltage	_	25	V
Vi	RF input voltage	_	65	dBmV
T _{stg}	storage temperature	-40	+100	°C
T _{mb}	operating mounting base temperature	-20	+100	°C

860 MHz, 18.5 dB gain power doubler amplifier

BGD802

CHARACTERISTICS

Table 1 Bandwidth 40 to 860 MHz; $V_B = 24 \text{ V}$; $T_{case} = 35 \,^{\circ}\text{C}$; $Z_S = Z_L = 75 \,^{\Omega}$

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Gp	power gain	f = 50 MHz	18	18.5	19	dB
		f = 860 MHz	18.5	19.5	_	dB
SL	slope cable equivalent	f = 40 to 860 MHz	0.2	1.1	2	dB
FL	flatness of frequency response	f = 40 to 860 MHz	_	±0.2	±0.5	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	35	_	dB
		f = 80 to 160 MHz	18.5	31	_	dB
		f = 160 to 320 MHz	17	27	_	dB
		f = 320 to 640 MHz	15.5	22	_	dB
		f = 640 to 860 MHz	14	20	_	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	29.5	_	dB
		f = 80 to 160 MHz	18.5	29	_	dB
		f = 160 to 320 MHz	17	25.5	_	dB
		f = 320 to 640 MHz	15.5	23	_	dB
		f = 640 to 860 MHz	14	22	_	dB
s ₂₁	phase response	f = 50 MHz	-45	_	+45	deg
СТВ	composite triple beat	49 channels flat; $V_0 = 47 \text{ dBmV}$; measured at 859.25 MHz	_	-66	-63	dB
X _{mod}	cross modulation	49 channels flat; $V_0 = 47 \text{ dBmV}$; measured at 55.25 MHz	_	-65	-62	dB
CSO	composite second order distortion	49 channels flat; V _o = 47 dBmV; measured at 860.5 MHz	_	-67.5	-60	dB
d_2	second order distortion	note 1	_	-75	-69	dB
Vo	output voltage	d _{im} = −60 dB; note 2	61.5	63.5	_	dBmV
NF	noise figure	f = 50 MHz	_	4.5	5.5	dB
		f = 550 MHz	_	_	6	dB
		f = 650 MHz	_	_	7	dB
		f = 750 MHz	_	_	7.5	dB
		f = 860 MHz	_	6.5	9	dB
I _{tot}	total current consumption (DC)	note 3	_	395	410	mA

Notes

```
1. f_p = 55.25 \text{ MHz}; V_p = 44 \text{ dBmV};

f_q = 805.25 \text{ MHz}; V_q = 44 \text{ dBmV};

measured at f_p + f_q = 860.5 \text{ MHz}.
```

2. Measured according to DIN45004B:

```
\begin{split} &f_p = 851.25 \text{ MHz; } V_p = V_o; \\ &f_q = 858.25 \text{ MHz; } V_q = V_o - 6 \text{ dB;} \\ &f_r = 860.25 \text{ MHz; } V_r = V_o - 6 \text{ dB;} \\ &\text{measured at } f_p + f_q - f_r = 849.25 \text{ MHz.} \end{split}
```

3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

860 MHz, 18.5 dB gain power doubler amplifier

BGD802

Table 2 Bandwidth 40 to 860 MHz; $V_B = 24$ V; $T_{case} = 30$ °C; $Z_S = Z_L = 75$ Ω

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Gp	power gain	f = 50 MHz	18	18.5	19	dB
		f = 860 MHz	18.5	19.5	_	dB
SL	slope cable equivalent	f = 40 to 860 MHz	0.2	1.1	2	dB
FL	flatness of frequency response	f = 40 to 860 MHz	_	±0.2	±0.5	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	35	_	dB
		f = 80 to 160 MHz	18.5	31	_	dB
		f = 160 to 320 MHz	17	27	_	dB
		f = 320 to 640 MHz	15.5	22	_	dB
		f = 640 to 860 MHz	14	20	_	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	29.5	_	dB
		f = 80 to 160 MHz	18.5	29	_	dB
		f = 160 to 320 MHz	17	25.5	_	dB
		f = 320 to 640 MHz	15.5	23	_	dB
		f = 640 to 860 MHz	14	22	_	dB
s ₂₁	phase response	f = 50 MHz	-45	_	+45	deg
СТВ	composite triple beat	129 channels flat; V _o = 44 dBmV; measured at 859.25 MHz	_	-56.5	-54	dB
X _{mod}	cross modulation	129 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	_	-61	-59	dB
CSO	composite second order distortion	129 channels flat; V _o = 44 dBmV; measured at 860.5 MHz	_	-64.5	-56	dB
d ₂	second order distortion	note 1	=	−75	-69	dB
Vo	output voltage	$d_{im} = -60 \text{ dB}$; note 2	61.5	63	_	dBmV
NF	noise figure	see Table 1	_	Ī-	_	dB
I _{tot}	total current consumption (DC)	note 3	_	395	410	mA

Notes

```
 \begin{array}{ll} \text{1.} & f_p = 55.25 \text{ MHz}; \ V_p = 44 \text{ dBmV}; \\ f_q = 805.25 \text{ MHz}; \ V_q = 44 \text{ dBmV}; \\ & \text{measured at } f_p + f_q = 860.5 \text{ MHz}. \end{array}
```

2. Measured according to DIN45004B:

```
\begin{split} f_p &= 851.25 \text{ MHz; } V_p = V_o; \\ f_q &= 858.25 \text{ MHz; } V_q = V_o - 6 \text{ dB;} \\ f_r &= 860.25 \text{ MHz; } V_r = V_o - 6 \text{ dB;} \\ \text{measured at } f_p + f_q - f_r = 849.25 \text{ MHz.} \end{split}
```

3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

860 MHz, 18.5 dB gain power doubler amplifier

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Table 3 Bandwidth 40 to 750 MHz; $V_B = 24 \text{ V}$; $T_{case} = 30 \,^{\circ}\text{C}$; $Z_S = Z_L = 75 \,^{\circ}\Omega$

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G _p	power gain	f = 50 MHz	18	18.5	19	dB
·		f = 750 MHz	18.5	19.4	_	dB
SL	slope cable equivalent	f = 40 to 750 MHz	0.2	_	2	dB
FL	flatness of frequency response	f = 40 to 750 MHz	_	_	±0.5	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	35	_	dB
		f = 80 to 160 MHz	18.5	31	_	dB
		f = 160 to 320 MHz	17	27	_	dB
		f = 320 to 640 MHz	15.5	22	_	dB
		f = 640 to 750 MHz	14	20	_	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	29.5	_	dB
		f = 80 to 160 MHz	18.5	29	_	dB
		f = 160 to 320 MHz	17	25.5	_	dB
		f = 320 to 640 MHz	15.5	23	-	dB
		f = 640 to 750 MHz	14	22	_	dB
s ₂₁	phase response	f = 50 MHz	-45	_	+45	deg
СТВ	composite triple beat	110 channels flat; V _o = 44 dBmV; measured at 745.25 MHz	_	-60.5	-58	dB
X _{mod}	cross modulation	110 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	_	-62.5	-60	dB
CSO	composite second order distortion	110 channels flat; V _o = 44 dBmV; measured at 746.5 MHz	_	-66	-60	dB
d ₂	second order distortion	note 1	_	_	-72	dB
Vo	output voltage	$d_{im} = -60 \text{ dB}$; note 2	64	_	_	dBmV
NF	noise figure	see Table 1	_	_	_	dB
I _{tot}	total current consumption (DC)	note 3	_	395	410	mA

Notes

```
1. f_p = 55.25 MHz; V_p = 44 dBmV; f_q = 691.25 MHz; V_q = 44 dBmV; measured at f_p + f_q = 746.5 MHz.
```

2. Measured according to DIN45004B:

```
\begin{split} f_p &= 740.25 \text{ MHz; } V_p = V_o; \\ f_q &= 747.25 \text{ MHz; } V_q = V_o - 6 \text{ dB;} \\ f_r &= 749.25 \text{ MHz; } V_r = V_o - 6 \text{ dB;} \\ \text{measured at } f_p + f_q - f_r = 738.25 \text{ MHz.} \end{split}
```

3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

860 MHz, 18.5 dB gain power doubler amplifier

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Table 4 Bandwidth 40 to 550 MHz; $V_B = 24 \text{ V}$; $T_{case} = 30 \,^{\circ}\text{C}$; $Z_S = Z_L = 75 \,^{\circ}\Omega$

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Gp	power gain	f = 50 MHz	18	18.5	19	dB
		f = 550 MHz	18.5	19.3	_	dB
SL	slope cable equivalent	f = 40 to 550 MHz	0.2	_	2	dB
FL	flatness of frequency response	f = 40 to 550 MHz	_	_	±0.3	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	35	_	dB
		f = 80 to 160 MHz	18.5	31	_	dB
		f = 160 to 320 MHz	17	27	_	dB
		f = 320 to 550 MHz	16	22	_	dB
S ₂₂	input return losses	f = 40 to 80 MHz	20	29.5	_	dB
		f = 80 to 160 MHz	18.5	29	_	dB
		f = 160 to 320 MHz	17	25.5	_	dB
		f = 320 to 550 MHz	16	23	_	dB
s ₂₁	phase response	f = 50 MHz	-45	_	+45	deg
СТВ	composite triple beat	77 channels flat; V _o = 44 dBmV; measured at 547.25 MHz	-	-67	-65	dB
X _{mod}	cross modulation	77 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	_	-66	-63	dB
CSO	composite second order distortion	77 channels flat; V _o = 44 dBmV; measured at 548.5 MHz	_	-67	-63	dB
d_2	second order distortion	note 1	_	_	-72	dB
Vo	output voltage	$d_{im} = -60 \text{ dB}$; note 2	65	_	_	dBmV
NF	noise figure	see Table 1	_	_	=	dB
I _{tot}	total current consumption (DC)	note 3	_	395	410	mA

Notes

```
1. f_p = 55.25 MHz; V_p = 44 dBmV; f_q = 493.25 MHz; V_q = 44 dBmV; measured at f_p + f_q = 548.5 MHz.
```

2. Measured according to DIN45004B:

```
\begin{split} f_p &= 540.25 \text{ MHz; } V_p = V_o; \\ f_q &= 547.25 \text{ MHz; } V_q = V_o - 6 \text{ dB;} \\ f_r &= 549.25 \text{ MHz; } V_r = V_o - 6 \text{ dB;} \\ \text{measured at } f_p + f_q - f_r = 538.25 \text{ MHz.} \end{split}
```

3. The module normally operates at $V_B = 24 \text{ V}$, but is able to withstand supply transients up to 30 V.

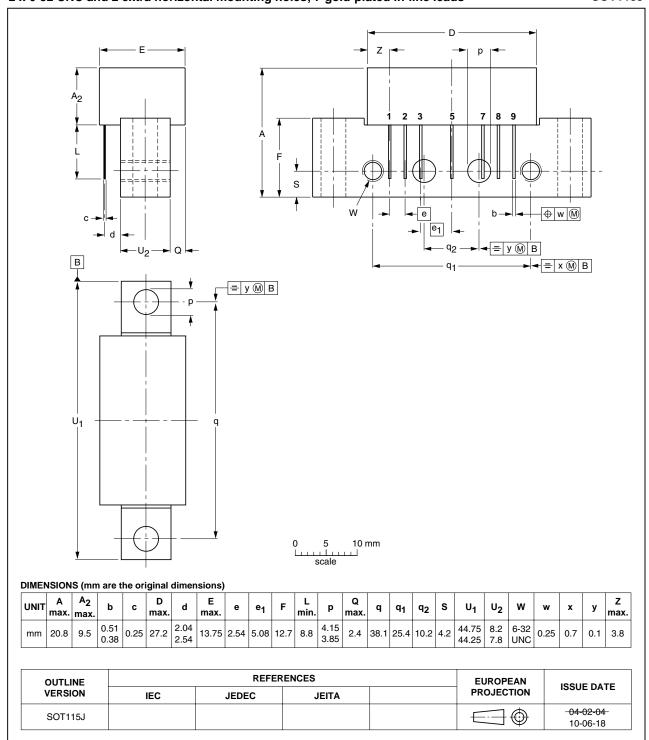
860 MHz, 18.5 dB gain power doubler amplifier

BGD802

PACKAGE OUTLINE

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads

SOT115J



860 MHz, 18.5 dB gain power doubler amplifier

BGD802

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.

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860 MHz, 18.5 dB gain power doubler amplifier

BGD802

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Contact information

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